### 9.0 ELECTRICAL CHARACTERISTICS

## 9.1 Absolute Maximum Ratings†

Ambient temperature under bias	55°C to +125°C
Storage temperature	65°C to +150°C
Voltage on VDD with respect to Vss	0 to +7.5V
Voltage on MCLR with respect to Vss	0 to +14V
Voltage on all other pins with respect to Vss	0.6V to Vop + 0.6V
Total power dissipation (Note 1)	800 mW
Max. current out of Vss pin	
Max. current into VDD pin	50 mA
Max. current into an input pin (TOCKI only)	±500 μA
Input clamp current, lik (VI < 0 or VI > VDD)	±20 mA
Output clamp current, loκ (V0 < 0 or V0 > VDD)	±20 mA
Max. output current sunk by any I/O pin	25 mA
Max. output current sourced by any I/O pin	20 mA
Max. output current sourced by a single I/O port (PORTA, B or C)	40 mA
Max. output current sunk by a single I/O port (PORTA, B or C)	50 mA

Note 1: Total power dissipation should not exceed 800 mW for the package. Power dissipation is calculated as follows:

Pdis = VDD x {IDD -  $\sum$  IOH} +  $\sum$  {(VDD-VOH) x IOH} +  $\sum$ (VOL x IOL)

<sup>†</sup>NOTICE: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 9-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)

osc	16C5X-04	16C5X-10	16C5X-20	16LC5X-04
RC	VDD: 3.0V to 6.25V IDD: 2.4 mA Max. at 5.5V IPD: 4 μA Max. at 3.0V WDT dis Freq: 4 MHz Max.	VDD: 4.5V to 5.5V IDD: 1.7 mA typ. at 5.5V IPD: 0.25 μA typ. at 3.0V WDT dis Freq: 4 MHz Max.	VDD: 4.5V to 5.5V IDD: 1.7 mA typ. at 5.5V IPD: 0.25 μA typ. at 3.0V WDT dis Freq: 4 MHz Max.	VDD: 2.5V to 6.25V IDD: 0.5 mA typ. at 5.5V IPD: 4 μA Max. at 2.5V WDT dis Freq: 2 MHz Max.
хт	VDD: 3.0V to 6.25V IDD: 2.4 mA Max. at 5.5V IPD: 5 μA Max. at 3.0V WDT dis Freq: 4 MHz Max.	VDD: 4.5V to 5.5V IDD: 1.7 mA typ. at 5.5V IPD: 0.25 μA typ. at 3.0V WDT dis Freq: 4 MHz Max.	VDD: 4.5V to 5.5V IDD: 1.7 mA typ. at 5.5V IPD: 0.25 μA typ. at 3.0V WDT dis Freq: 4 MHz Max.	VDD: 2.5V to 6.25V IDD: 0.5 mA typ. at 5.5V IPD: 4 µA Max. at 2.5V WDT dis Freq: 4 MHz Max.
HS	VDD: 4.5V to 5.5V IDD: 1.8 mA typ. at 5.5V IPD: 0.3 µA typ. at 3.0V WDT dis Freq: 4 MHz Max.	VDD: 4.5V to 5.5V IDD: 8 mA Max. at 5.5V IPD: 4 μA Max. at 3.0V WDT dis Freq: 10 MHz Max.	VDD: 4.5V to 5.5V IDD: 16 mA Max. at 5.5V IPD: 4 μA Max. at 3.0V WDT dis Freq: 20 MHz Max.	Do not use in HS mode
LP	VDD: 4.5V to 5.5V IDD: 17 μA typ. at 32 kHz, 3.0V IPD: 0.3 μA typ. at 3.0V WDT dis Freq: 200 kHz typ.	Do not use in LP mode	Do not use in LP mode	VDD: 2.5V to 6.25V IDD: 11 μA typ. at 32 kHz, 2.5V IPD: 0.25 μA typ. at 2.5V WDT dis Freq: 200 kHz typ.

The shaded sections indicate oscillator selections which are tested for functionality, but not for MIN/MAX specifications. It is recommended that the user select the device type that guarantees the specifications required.

TABLE 9-2: DC CHARACTERISTICS: PIC16C5X-RC, XT, HS, LP (COMMERCIAL)

DC Characteristics Power Supply Pins	Standard Operating Conditions  Operating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ , unless otherwise stated.  Operating Voltage VDD = 3.0V to 5.5V, unless otherwise stated.						
Characteristic	Sym	Min	Typ (Note 1)	Max	Units	Conditions	
Supply Voltage							
PIC16C5X-XT	VDD	3.0		6.25	V	Fosc = DC to 4 MHz	
PIC16C5X-RC		3.0		6.25	V	Fosc = DC to 4 MHz	
PIC16C5X-HS		4.5		5.5	V	Fosc = DC to 20 MHz	
PIC16C5X-LP		2.5		6.25	V	Fosc = DC to 40 kHz	
RAM Data Retention Voltage (Note 3)	VDR		1.5		٧	Device in SLEEP mode	
Vpp start voltage to guaran- tee Power-On Reset	VPOR		Vss		٧	See Section 7.4 for details on Power- On Reset	
VDD rise rate to guarantee Power-On Reset	SVDD	0.05*			V/ms	See Section 7.4 for details on Power- On Reset	
Supply Current (Note 2)							
PIC16C5X-XT	IDD		1.8	3.3	mA	Fosc = 4 MHz, VDD = 5.5V	
PIC16C5X-RC (Note 5)		1	1.8	3.3	mA	Fosc = 4 MHz, VDD = 5.5V	
PIC16C5X-HS		1	4.8	10	mA	Fosc = 10 MHz, VDD = 5.5V	
			9.0	20	mA	Fosc = 20 MHz, VDD = 5.5V	
PIC16C5X-LP			15	32	μА	Fosc = 32 kHz, VDD = 3.0V, WDT disabled	
Power Down Current (Note 4)							
PIC16C5X	IPD		4	12	μA	VDD = 3.0V, WDT enabled	
			0.6	9	μA	VDD = 3.0V, WDT disabled	

- \* These parameters are based on characterization and are not tested.
- Note 1: Data in the column labeled "Typical" is based on characterization results at 25°C. This data is for design guidance only and is not tested for, or guaranteed by Microchip Technology.
  - The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern, and temperature also have an impact on the current consumption.
    - a) The test conditions for all IDD measurements in active operation mode are:
    - OSC1=external square wave, from rail to rail; all I/O pins tristated, pulled to Vbb, T0CKI = Vbb, MCLR = Vbb; WDT enabled/disabled as specified.
    - b) For stand-by current measurements, the conditions are the same, except that the device is in SLEEP mode.
  - 3: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
  - 4: The power down current in SLEEP mode does not depend on the oscillator type. Power down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to Vbb and Vss.
  - 5: Does not include current through Rext. The current through the resistor can be estimated by the formula: IR = VDD/2Rext (mA) with Rext in kOhm.

TABLE 9-3: DC CHARACTERISTICS: PIC16C5XI-RC, XT, HS, LP (INDUSTRIAL)

DC Characteristics Power Supply Pins	Standard Operating Conditions  Operating Temperature -40°C ≤ TA ≤ +85°C, unless otherwise stated.  Operating Voltage VDD = 3.5V to 5.5V, unless otherwise stated.						
Characteristic	Sym	Min	Typ (Note 1)	Max	Units	Conditions	
Supply Voltage							
PIC16C5XI-XT	Voo	3.0		6.25	٧	Fosc = DC to 4 MHz	
PIC16C5XI-RC		3.0		6.25	V	Fosc = DC to 4 MHz	
PIC16C5XI-HS		4.5		5.5	V	Fosc = DC to 20 MHz	
PIC16C5XI-LP		2.5		6.25	V	Fosc = DC to 40 kHz	
RAM Data Retention Voltage (Note 3)	VDR		1.5		٧	Device in SLEEP mode	
VDD start voltage to guarantee Power-On Reset	VPOR		Vss		٧	See Section 7.4 for details on Power- On Reset	
Voo rise rate to guarantee Power-On Reset	SVDD	0.05*			V/ms	See Section 7.4 for details on Power- On Reset	
Supply Current (Note 2)							
PIC16C5XI-XT	DD		1.8	3.3	mA	Fosc = 4 MHz, VDD = 5.5V	
PIC16C5XI-RC (Note 5)		1	1.8	3.3	mA	Fosc = 4 MHz, VDD = 5.5V	
PIC16C5XI-HS			4.8	10	mA	Fosc = 10 MHz, VDD = 5.5V	
			9.0	20	mA	Fosc = 20 MHz, VDD = 5.5V	
PIC16C5XI-LP			19	40	μА	Fosc = 32 kHz, VDD = 3.0V, WDT disabled	
Power Down Current (Note 4)							
PIC16C5XI	IPD		5	14	μΑ	VDD = 3.0V, WDT enabled	
			0.6	12	μΑ	VDD = 3.0V, WDT disabled	

<sup>\*</sup> These parameters are based on characterization and are not tested.

- Note 1: Data in the column labeled "Typical" is based on characterization results at 25°C. This data is for design guidance only and is not tested for, or guaranteed by Microchip Technology.
  - The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern, and temperature also have an impact on the current consumption.
    - a) The test conditions for all IDD measurements in active operation mode are: OSC1=external square wave, from rail to rail; all I/O pins tristated, pulled to Vbb, T0CKI = Vbb,
    - MCLR = VDD; WDT enabled/disabled as specified.
      b) For stand-by current measurements, the conditions are the same, except that the device is in SLEEP mode.
  - 3: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
  - 4: The power down current in SLEEP mode does not depend on the oscillator type. Power down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to Vod and Vss.
  - 5: Does not include current through Rext. The current through the resistor can be estimated by the formula: IR = VDD/2Rext (mA) with Rext in kOhm.

TABLE 9-4: DC CHARACTERISTICS: PIC16C5XE-RC, XT, HS, LP (AUTOMOTIVE)

DC Characteristics Power Supply Pins		Standard Operating Conditions  Operating Temperature -40°C ≤ TA ≤ +125°C, unless otherwise stated.  Operating Voltage VDD = 3.5V to 5.5V, unless otherwise stated.						
Characteristic	Sym	Min	Typ (Note 1)	Max	Units	Conditions		
Supply Voltage								
PIC16C5XE-XT	VDD	3.25		6.0	V	Fosc = DC to 4 MHz		
PIC16C5XE-RC		3.25		6.0	V	Fosc = DC to 4 MHz		
PIC16C5XE-HS		4.5		5.5	V	Fosc = DC to 20 MHz		
PIC16C5XE-LP		2.5		6.0	V	Fosc = DC to 40 kHz		
RAM Data Retention Voltage (Note 3)	VDR		1.5		V	Device in SLEEP mode		
VDD Start Voltage to Guarantee Power-On Reset	VPOR		Vss		V	See Section 7.4 for details on Power- On Reset		
VDD rise rate to guarantee Power-On Reset	SVDD	0.05*			V/ms	See Section 7.4 for details on Power- On Reset		
Supply Current (Note 2)								
PIC16C5XE-XT	IDD		1.8	3.3	mA	Fosc = 4 MHz, VDD = 5.5V		
PIC16C5XE-RC (Note 5)			1.8	3.3	mA	Fosc = 4 MHz, VDD = 5.5V		
PIC16C5XE-HS			4.8	10	mA	Fosc = 10 MHz, VDD = 5.5V		
			9.0	20	mA	Fosc = 16 MHz, VDD = 5.5V		
PIC16C5XE-LP			25	55	μA	Fosc = 32 kHz, VDD = 3.25V, WDT disabled		
Power Down Current (Note 4)								
PIC16C5XE	IPD		5	22	μA	VDD = 3.25V, WDT enabled		
			0.8	18	μA	VDD = 3.25V, WDT disabled		

<sup>\*</sup> These parameters are based on characterization and are not tested.

- Note 1: Data in the column labeled "Typical" is based on characterization results at 25°C. This data is for design guidance only and is not tested for, or guaranteed by Microchip Technology.
  - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern, and temperature also have an impact on the current consumption.
    - a) The test conditions for all IDD measurements in active operation mode are:
    - OSC1=external square wave, from rail to rail; all I/O pins tristated, pulled to Vbb, T0CKI = Vbb, MCLR = Vbb; WDT enabled/disabled as specified.
    - b) For stand-by current measurements, the conditions are the same, except that the device is in SLEEP mode.
  - 3: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
  - 4: The power down current in SLEEP mode does not depend on the oscillator type. Power down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and Vss.
  - 5: Does not include current through Rext. The current through the resistor can be estimated by the formula: IR = VDD/2Rext (mA) with Rext in kOhm.

TABLE 9-5: DC CHARACTERISTICS:PIC16C5X-RC, XT, HS, LP (COMMERCIAL)
PIC16C5XI-RC, XT, HS, LP (INDUSTRIAL)

Standard Operating Conditions **DC Characteristics** Operating Temperature  $-40^{\circ}$ C  $\leq$  TA  $\leq$  +85°C (for industrial) All Pins Except Power Supply 0°C ≤ TA ≤ +70°C (for commercial) Pins Operating Voltage VDD range is described in Section 9.1 and Section 9.2. Typ Characteristic Sym Min Max Units Conditions (Note 1) Input Low Voltage I/O ports VII Vss 0.2 VDD V Pin at hi-impedance MCLR (Schmitt Trigger) Vss 0.15 VDD V TOCKI (Schmitt Trigger) Vss 0.15 VDD ٧ OSC1 (Schmitt Trigger) Vss 0.15 VDD V PIC16C5X-RC only (Note 5) OSC<sub>1</sub> Vss 0.3 Vpp V PIC16C5X-XT, HS, LP Input High Voltage I/O ports Vін 0.45 VDD Vnn ٧ For all VDD (Note 6) 2.0 VDD ٧  $4.0V < VDD \le 5.5V \text{ (Note 6)}$ 0.36 VDD VDD ν VDD > 5.5VMCLR (Schmitt Trigger) 0.85 VDD VDD ν TOCKI (Schmitt Trigger) 0.85 VDD VDD ٧ OSC1 (Schmitt Trigger) 0.85 Vpp Vnn ν PIC16C5X-RC only (Note 5) OSC<sub>1</sub> 0.7 VDD VDD V PIC16C5X-XT, HS, LP Input Leakage Current For VDD  $\leq 5.5$ V (Notes 3,4) I/O ports lıL -1 0.5 +1 μΑ  $Vss \leq Vpin \leq Vdd$ . Pin at hi-impedance MCLR -5 μΑ VPIN = VSS + 0.25V**MCLR** 0.5 VPIN = VDD +5 μА TOCKI -3 0.5  $Vss \le Vpin \le Vdd$ +3 μΑ OSC1 -3 0.5 +3 μΑ  $Vss \leq Vpin \leq Vdd$ PIC16C5X-XT, HS, LP Output Low Voltage I/O ports Vol 0.6 V IOL = 8.7 mA, VDD = 4.5VOSC2/CLKOUT 0.6 v IOL = 1.6 mA, VDD = 4.5V(PIC16C5X-RC) Output High Voltage I/O ports (Note 4) Vон VDD-0.7 V IOH = -5.4 mA, VDD = 4.5VOSC2/CLKOUT VDD-0.7 IOH = -1.0 mA, VDD = 4.5V(PIC16C5X-RC)

- Note 1: Data in the column labeled "Typical" is based on characterization results at 25°C. This data is for design guidance only and is not tested for, or guaranteed by Microchip Technology.
  - 2: Total power dissipation as stated under absolute maximum ratings must not be exceeded.
  - The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.
  - 4: Negative current is defined as coming out of the pin.
  - 5: For PIC16C5X-RC devices, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C5X be driven with external clock in RC mode.
  - 6: The user may use the better of the two specifications.

TABLE 9-6: DC CHARACTERISTICS: PIC16C5X-RC, XT, HS, LP (AUTOMOTIVE)

DC Characteristics All Pins Except Power S Pins	-	Operating T	Standard Operating Conditions  Operating Temperature -40°C ≤ TA ≤ +125°C  Operating Voltage VDD range is described in Section 9.1 and Section 9.2.							
Characteristic Sym		n Min Typ Max Units		Conditions						
Input Low Voltage										
I/O ports	VIL	Vss		0.15 VDD	V	Pin at hi-impedance				
MCLR (Schmitt Trigger)		Vss		0.15 VDD	V					
T0CKI (Schmitt Trigger)		Vss	]	0.15 VDD	V					
OSC1 (Schmitt Trigger)		Vss		0.15 VDD	V	PIC16C5X-RC only (Note 5)				
OSC1		Vss		0.3 VDD	V	PIC16C5X-XT, HS, LP				
Input High Voltage										
I/O ports	ViH	0.45 VDD		VDD	l v	For all VDD (Note 6)				
		2.0		Voo	V	4.0V < VDD ≤ 5.5V (Note 6)				
		0.36 VDD		Vod	V	VDD > 5.5V				
MCLR (Schmitt Trigger)		0.85 VDD		Vod	v					
T0CKI (Schmitt Trigger)		0.85 VDD		Vod	l v					
OSC1 (Schmitt Trigger)		0.85 VDD	1	Vod	l v	PIC16C5X-RC only (Note 5)				
OSC1		0.7 VDD		VDD	V	PIC16C5X-XT, HS, LP				
Input Leakage Current				,		For VDD ≤ 5.5V				
(Notes 3,4)										
I/O ports	IIL	-1	0.5	+1	μA	VSS ≤ VPIN ≤ VDD,				
						Pin at hi-impedance				
MCLR		-5			μA	VPIN = VSS + 0.25V				
MCLR			0.5	+5	μA	VPIN = VDD				
T0CKI		-3	0.5	+3	μA	VSS ≤ VPIN ≤ VDD				
OSC1		-3	0.5	+3	μA	VSS ≤ VPIN ≤ VDD				
			1			PIC16C5X-XT, HS, LP				
Output Low Voltage										
I/O ports	VOL			0.6	v	IOL = 8.7 mA, VDD = 4.5V				
OSC2/CLKOUT			1	0.6	v	IOL = 1.6 mA, VDD = 4.5V				
(PIC16C5X-RC)										
Output High Voltage					1					
I/O ports (Note 4)	Vон	VDD-0.7			v	IOH = -5.4 mA, VDD = 4.5V				
OSC2/CLKOUT		VDD-0.7			v	IOH = -1.0 mA, VDD = 4.5V				
(PIC16C5X-RC)										

- Note 1: Data in the column labeled Typical is based on characterization results at 25°C. This data is for design guidance only and is not tested for, or guaranteed by Microchip Technology.
  - 2: Total power dissipation as stated under absolute maximum ratings must not be exceeded.
  - 3: The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.
  - 4: Negative current is defined as coming out of the pin.
  - 5: For PIC16C5X-RC devices, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C5X be driven with external clock in RC mode.
  - 6: The user may use the better of the two specifications.

# 9.2 <u>Timing Diagrams and Specifications</u>

### FIGURE 9-1: LOAD CONDITIONS

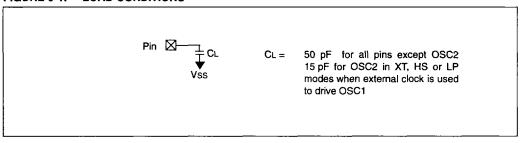


FIGURE 9-2: EXTERNAL CLOCKTIMING

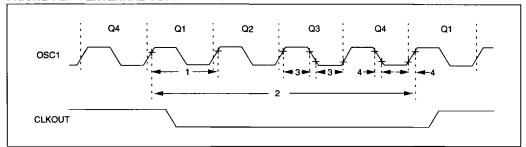


TABLE 9-7: EXTERNAL CLOCK TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
	Fosc	External CLKIN Frequency	DC		4	MHz	RC osc mode
		(Note 1)	DC		4	MHz	XT osc mode
			DC	-	20	MHz	HS osc mode (Comm/Indust)
			DC	-	16	MHz	HS osc mode (Automotive)
			DC	-	40	kHz	LP osc mode
		Oscillator Frequency	DC		4	MHz	RC osc mode
		(Note 1)	0.1		4	MHz	XT osc mode
			4	—	20	MHz	HS osc mode (Comm/Indust)
			4	_	16	MHz	HS osc mode (Automotive)
			5		40	kHz	LP osc mode
1	Tosc	External CLKIN Period	250	_		ns	RC osc mode
		(Note 1)	250	_		ns	XT osc mode
			50			ns	HS osc mode
			100	—	_	μs	LP osc mode
		Oscillator Period	250	_	_	ns	RC osc mode
		(Note 1)	250	<b> </b>	10,000	ns	XT osc mode
			62.5		250	ns	HS osc mode (Comm/Indust)
			50	-	250	ns	HS osc mode (Automotive)
			100	_	200	μs	LP osc mode
2	Tcy	Instruction Cycle Time (Note 1)	1.0	_	DC	μs	
3	TasL, TosH	Clock in (OSC1) Low or High Time	50			ns	XT oscillator
			2.5	-	-	μs	LP oscillator
			10	-		ns	HS oscillator
4	TosR, TosF	Clock in (OSC1) Rise or Fall Time	25	_		ns	XT oscillator
			50	-		ns	LP oscillator
			15	_		ns	HS oscillator

<sup>†</sup> Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

Note 1: Instruction cycle period (TcY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/ or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin.

FIGURE 9-3: CLKOUT AND VO TIMING

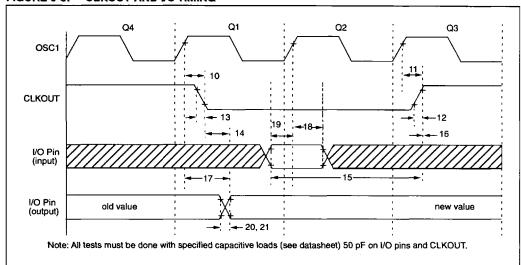


TABLE 9-8: CLKOUT AND I/O TIMING REQUIREMENTS

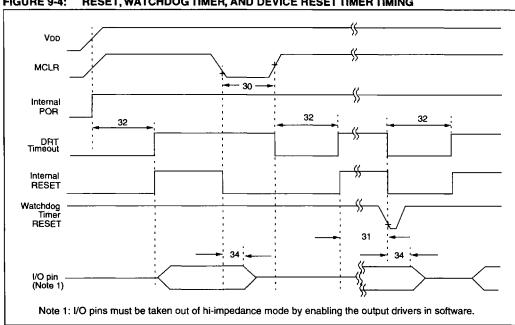
Parameter No.	Sym	Characteristic	Min	Typt	Max	Units	Conditions
10	TosH2ckL	OSC1↑ to CLKOUT↓	_	15	30	ns	Note 1
11	TosH2ckH	OSC1T to CLKOUTT		15	30	ns	Note 1
12	TckR	CLKOUT rise time	_	5	15	ns	Note 1
13	TckF	CLKOUT fall time	-	5	15	ns	Note 1
14	TckL2ioV	CLKOUT↓ to Port out valid	_	_	0.5 TCY+20	ns	Note 1
15	TioV2ckH	Port in valid before CLKOUT1	0.25 TCY+25	_	-	ns	Note 1
16	TckH2iol	Port in hold after CLKOUT	0	_		ns	Note 1
17	TosH2ioV	OSC1T (Q1 cycle) to Port out valid		_	80 - 100	ns	Note 2
18	TosH2iol	OSC1 <sup>↑</sup> (Q2 cycle) to Port input invalid (I/O in hold time)	TBD	_		ns	
19	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	TBD	_	-	ns	
20	TioR	Port output rise time		10	25	ns	Note 2
21	TioF	Port output fall time		10	25	ns	Note 2

These parameters are characterized but not tested.

<sup>†</sup> Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x Tosc.

<sup>2:</sup> See Figure 9-1 for loading conditions.



RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER TIMING FIGURE 9-4:

RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER **TABLE 9-9:** 

Parameter No.	Sym	Characteristic	Min	Typt	Max	Units	Conditions
30	TmcL	MCLR Pulse Width (low)	100	-	_	ns	VDD = 5V, -40°C to +125°C
31	Twdt	Watchdog Timer Timeout Period (No Prescaler)	9*	18	30*	ms	VDD = 5V, -40°C to +125°C
32	TDAT	Device Reset Timer Period	9*	18*	30*	ms	VDD = 5V, -40°C to +125°C
34	Tioz	I/O Hi-impedance from MCLR Low			100	ns	

These parameters are characterized but not tested.

t Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

# FIGURE 9-5: TIMERO CLOCK TIMINGS

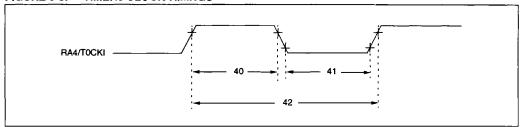


TABLE 9-10: TIMERO CLOCK REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Тур†	Max	Units	Conditions
40	TIOH	T0CKI High Pulse Width	No Prescaler	0.5 Tcy + 20*	=		ns	
			With Prescaler	10*	<b> </b>	_	ns	
41	TtOL	T0CKI Low Pulse Width	No Prescaler	0.5 Tcy + 20*			ns	
			With Prescaler	10*	-	_	ns	
42	TtoP	T0CKI Period	•	TCY + 40* N	-	_		N = prescale value (1, 2, 4,, 256)

These parameters are characterized but not tested.

<sup>†</sup> Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.